

## S-200

### FULL AUTOMATIC SCRIBER

The S200 is a robust, vibration-free automatic scriber designed for easy operation and flexible processing of components in different sizes. Video-assisted vertical targeting, programmable movement and motorized wafer rotation provide accurate and repeatable scribing with minimal operator training. The large wafer table supports wafers and substrates up to 8 inches, making the S200 suitable for research, process development and production environments.



AUTOMATIC SCRIBING

VISION ALIGNMENT

MOTORIZED ROTATION

WAFERS UP TO 8 INCHES

### Flexible by design

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#### KEY BENEFITS

- Processes wafers and substrates up to 8 inches
- Adjustable scribing force from 10 to 300 g
- Motorized and programmable wafer rotation
- High-definition vision alignment system
- Programmable scribing speed and length
- Suitable for a wide range of materials

#### Explore the possibilities

Contact Micronnect for configuration advice, a demonstration, training and service.

# Technology and configuration

Designed for high-precision scribing and alignment, the S200 combines motorized motion, digital vision and programmable process control for accurate handling of wafers and large substrates. The adjustable scribing head, motorized wafer table and advanced vision system provide the flexibility required for research, process development and production applications.

## 01 Precision Scribing

The motorized scribing head provides true vertical Z-motion with adjustable tool angle and rotation. Scribing force can be adjusted from 10 to 300 g to suit different materials and applications.

## 02 Advanced Vision

High-definition camera, programmable alignment and digital zoom provide precise targeting and positioning.

## 03 Flexible Wafer Handling

The vacuum wafer table supports wafers and substrates from 2 to 8 inches. A frame or ring adaptor can be used for alternative workpiece configurations.

## 04 Motorized Rotation

The wafer table provides continuous motorized rotation and programmable angular positioning. Fine theta alignment can be performed using two reference points.

### TECHNICAL DATA

|                      |                                       |
|----------------------|---------------------------------------|
| Wafer Size           | 2" to 8"                              |
| Wafer Holding        | Vacuum chuck                          |
| Scribing Head Motion | Motorized vertical Z-motion           |
| Scribing Force       | Adjustable from 10 to 300 g           |
| Tool Alignment       | Tool offset with electronic crosshair |
| Vision System        | Ultra-High_Definition Color Camera    |
| Dimensions           | 650 × 820 × 130 mm                    |
| Weight               | 70kg                                  |

*Specifications are based on the supplied product information. Final execution may vary by configuration.*

### OPTIONS

- Frame and ring adaptor
- Custom wafer chucks
- HD Side Inspection Camera
- Custom substrate holders
- Application-specific diamond tools

The integrated rotary table allows precise angular alignment of wafers, substrates and ceramic parts, improving scribing accuracy and process repeatability

**Find the right configuration for your process**

Contact us for technical advice or a demonstration.

**CONTACT**